

**LISTING OF CLAIMS:**

1. (Canceled)

2. (Canceled)

3. (Canceled)

4. (Currently amended)      The A heater-equipped pusher of claim 1 for pushing a terminal of an electronic component to be tested in an electronic component handling apparatus into a contact portion of a test head, comprising:

a pusher main body which is capable of direct contact with the electronic component to be tested;

a heat absorbing and radiating body provided on said pusher main body;

a heater provided on said pusher main body to enable direct or indirect contact with the electronic component to be tested without intervention of said pusher main body; and

a thermal insulating material provided between said pusher main body and said heater,

wherein the heater is disposed on a lower portion of the pusher main body so as to be exposed on a same plane as a lower surface of the pusher main body.

5. (Currently amended)      The ~~A~~ heater-equipped pusher for pushing a terminal of an electronic component to be tested in an electronic component handling apparatus into a contact portion of a test head, comprising:

a pusher main body which is capable of direct contact with the electronic component to be tested;

a heat absorbing and radiating body provided on said pusher main body;

a heater provided on said pusher main body to enable direct or indirect contact with the electronic component to be tested without intervention of said pusher main body; and

a thermal insulating material provided between said pusher main body and said heater of  
claim 1,

wherein the heat absorbing and radiating body is a heat sink.

6. (Previously presented)      The heater-equipped pusher of claim 5, wherein the heat sink includes a plurality of radiator fins.

7. (Previously presented)      The heater-equipped pusher of claim 5, wherein the heat sink includes a plurality of heat pipes.

8. (Canceled)

9. (Currently amended)      ~~The A~~ temperature control method for controlling the temperature of an electronic component to be tested during the testing of the electronic component in an electronic component handling apparatus, comprising:

cooling of the electronic component to be tested, performed by cooling a heat absorbing and radiating body to which the heat of the electronic component is transferred through a pusher main body, the pusher main body being in contact with the electronic component; and

heating of the electronic component to be tested, performed by a heater, and

preventing heat conduction from the heater to the pusher main body and the heat absorbing and radiating body by a thermal insulating material provided between the pusher main body and the heater~~of claim 3,~~

wherein the heater is disposed on a lower portion of the pusher main body so as to be exposed on a same plane as a lower surface of the pusher main body.

10. (Canceled)